ELEG 340 - Fall 08 Solid-State Electronics Quiz 3

23 October 2008

NAME Solution

Time Limit: 30 minutes

Closed Books and Notes. You may use your own calculator, but may not loan or borrow one (ask proctor if you have questions). Put expression in a final form as best you can.

Guidelines:

I. Full credit requires the final dimensions/ units for all numerical quantities that you calculate.

II. Show all work and calculations for full credit; accuracy to 2 significant figures is sufficient.

III. Assume that the material is silicon at room temperature (300 K), unless otherwise stated.

IV. At room temperature (300K), thermal energy $k_BT = 0.026$ eV, silicon has intrinsic concentration $n_i =$

1 (or 1.5) x 10^{10} cm⁻³, and recombination lifetimes: τ_n , $\tau_p = 1$ µsec; dielectric constant $\kappa_{Si} = 11.8$;.

Permittivity of free space $\varepsilon_0 = 8.85 \times 10^{-14}$ F/cm; electron charge $|q| = 1.6 \times 10^{-19}$ Coul;

V. Equations:

 $p_n(x_{no}) = p_{no}(x_{no})e^{qVf/kT};$

$$\begin{split} p_{op} &= i\hbar d/dx & f_{FD}(E) = I/[1 + exp(E-E_F)/k_BT] & E = Q \ V \\ n &= n_i exp[(E_F-E_i)/k_BT]. & p = n_i exp[(E_i-E_F)/k_BT] & n_o p_o = n_i^2 & np = n_i^2 e^{(Fn-Fp)/kBT} \\ J_n &= q\mu_n n \mathcal{E} + q D_n dn/dx & J_p = q\mu_p p \mathcal{E} - q D_p dp/dx & \sigma_{elec} = q(n\mu_n + p\mu_p) \\ U_n &= (n_p - n_{po})/\tau_n & U_p = (p_n - p_{no})/\tau_p & p' = p - p_o = g_{opt}\tau_p & n' = n - n_o = g_{opt}\tau_n \\ C_{dep} &= \kappa_s \epsilon_o \ A/W & C_{diff} = q I \tau/k_B T & D/\mu = k_B T/q & L = \sqrt{(D\tau)} \\ \partial p/\partial t &= -1/q \ \partial J_p/\partial x - p'/\tau_p & \partial n/\partial t = -1/q \ \partial J_n/\partial x - n'/\tau_n \ ; \\ \partial p/\partial t &= D_p \ \partial^2 p/\partial x^2 - p'/\tau_p & \partial n/\partial t = D_n \ \partial^2 n/\partial x^2 - n'/\tau_n & \mathcal{F} = \frac{1}{2} \mathcal{F$$

 $n_{p}(-x_{po}) = n_{po}(-x_{po})e^{qVf/kT}$

1. A sample of Ge at room temperature (300K) is p-type doped with $N_A = 1 \times 10^{16}$ cm⁻³, which are fully ionized. For Ge at 300 K, $n_i = 2.5 \times 10^{13}$ cm⁻³, hole mobility $\mu_p = 1900$ cm²/V-s, and electron mobility $\mu_p = 3900$ cm²/V-s. electron mobility $\mu_n = 3900$ cm²/V-s. Calculate the electrical conductivity, σ .

1. A sample of Ge at room temperature (300K) is
$$f(0) = 3$$
, hole mobility $f(0) = 300$ K, $f(0) = 300$ K, $f(0) = 300$ Cm²/V-s. Calculate the electrical conductivity, $f(0) = 300$ Cm²/V-s. Calculate the electrical conductivity, $f(0) = 300$ Cm²/V-s. $f(0) = 300$ Cm²V-s. $f(0) = 300$ Cm²V-s. $f(0) = 300$ Cm²V-s. $f(0) = 300$ Cm²V-s. $f(0) = 300$ Cm²

2. A one-sided step junction of silicon is uniformly doped with $N_A = 10^{18}$ cm⁻³ on the p-side, and $N_A = 10^{15}$ cm⁻³ on the p-side $N_A = 10^{15}$ A one-sided step junction of sincon is uniformly doped with $1NA = 10^{-10}$ on the p-side, and $ND = 10^{15}$ cm⁻³ on the n-side. Assume that the built-in (contact) voltage is $\Phi_{bi} = 0.7$ volts. What

2. A one-sided step junction of silicon is that the built-in (contact)
$$N_{D} = 10^{15} \text{ cm}^{3} \text{ on the n-side. Assume that the built-in (contact)}$$

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$$W = \sqrt{\frac{2 \times 560}{8}} \frac{496}{8}$$

$$= \sqrt{\frac{2 \times 11.8 \times 8.85 \times 0.7}{1.6 \times 10^{-19}}} \sqrt{\frac{17}{10^{-19}}} \sqrt{\frac{17}{10^{-19}}}} \sqrt{\frac{17}{10^{-19}}} \sqrt{\frac{17}{10^{-19}}}} \sqrt{\frac{17}{10^{-19}}} \sqrt{\frac{17}{10^{-19}$$

3. A junction of silicon has an equilibrium depletion width $W = 0.5 \mu m$. Calculate the depletion capacitance per area C'_{dep}, in thermal equilibrium. (Hint: the text calls C_{dep} the "junction" capacitance)

$$C' = \frac{K_5 \, f_0}{W} = \frac{11.8 \times 8.85 \times 10^{-14} \, F/cm}{0.5 \times 10^{-4} \, cm}$$

$$= 2 \times 1.18 \times 0.885 \times 10^{1+1-14+4} \, F/cm^2$$

$$= 1 \times 10^{-8} \, F/cm^2$$

4. Consider a one-sided step junction of silicon, uniformly doped with $N_A = 10^{18}$ cm⁻³ on the p-side, and $N_D = 10^{16}$ cm⁻³ on the n-side. (a) calculate the equilibrium concentration of minority holes at the depletion edge of the n-side, $p_{no}(x_{no})$. (b) using the law of the junction, calculate the new concentration of holes at the depletion edge $p_n(x_{no})$ under a forward bias $V_F = +0.5$ volts.

a)
$$P_{no} = \frac{h_1^2}{N_0} = \frac{10^{20} \text{ cm}^{-6}}{10^{16} \text{ cm}^{-3}} = 10^4 \text{ cm}^{-3}$$

5)
$$P_n(x_{n0}) = P_{n0} e^{cV/nT}$$

 $= 10^4 cm^{-3} e^{-3}$
 $= 20.5 \times 40 = 20$
 $= 20 = 10^8$
 $= 10^{12} cm^{-3}$

5. A junction of silicon under forward bias V_F has a concentration of minority holes at the depletion edge on the n-side, $p_n(x=x_{no})$ given by the law of the junction. The excess concentration of holes, $p_n'=p_n-p_{no}$, decays exponentially as $e^{-x/Lp}$. With this x-dependence, calculate an analytical expression for the diffusion current (only) of holes that flows under this concentration gradient. Hint: ignore any other currents that may be flowing.

 $\frac{1}{\sqrt{2p}} = -2 \frac{1}{\sqrt{2p}} = -2 \frac{1$

6. Sketch the I-V characteristics of a *real* (non-ideal) pn junction diode and label on your drawing the following regions: (a) forward bias; (b) reverse bias; (c) breakdown; (d) your choice of *one* other effect such as generation/recombination current, or Ohmic limit.

4 Columnia C

7. Sketch the band diagram of your choice of a metal-semiconductor junction, and indicate whether the semiconductor is n-type or p-type, and whether your band diagram shows a rectifying or Ohmic contact.

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